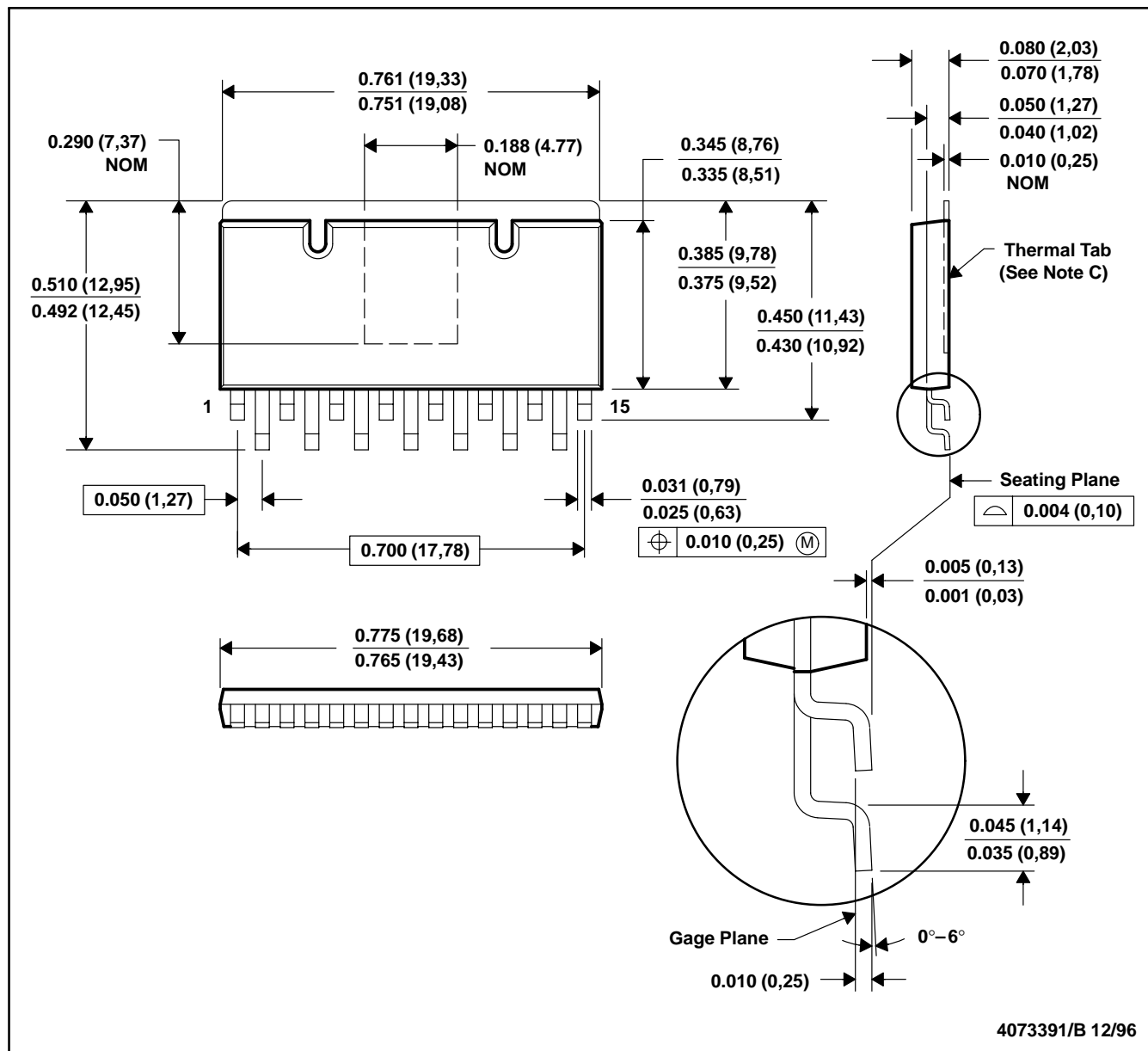


KTR (R-PSFM-G15)

PowerFLEX™ PLASTIC FLANGE-MOUNT PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. The heat sink area is approx 78K sq mils.
 D. Dimensions do not include mold protrusions (not to exceed 0.006 (0,15)).

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